

Part Number: XZDG60W

3.0mmx1.5mm SMD CHIP LED LAMP

Features

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

ullet Package : 2000pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant

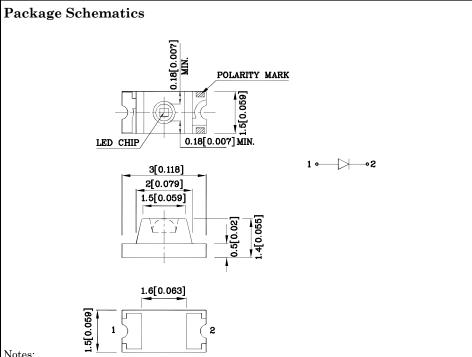






ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE

DEVICES



- Notes:
- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	DG (InGaN)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	P_D	102.5	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshold (HBM)	450	V		

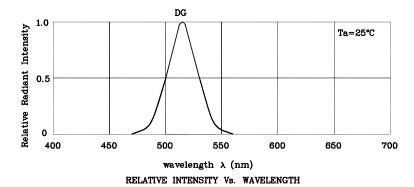
Operating Characteristics (T _A =25°C)		DG (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4.1	V
Reverse Current (Max.) $(V_R=5V)$	I_R	50	uA
Wavelength of Peak Emission (Typ.) $(I_F=20 \text{mA})$	λΡ	515	nm
Wavelength of Dominant Emission (Typ.) $(I_F=20 \text{mA})$	λD	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	45	pF

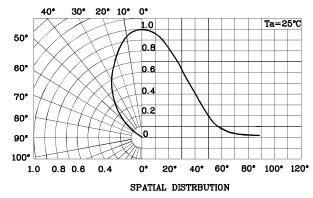
Part Number	Emitting Color	Emitting Material	Lens-color	Inter	inous nsity 0mA) cd	Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZDG60W	Green	InGaN	Water Clear	500	795	515	70°

Apr 23,2011 XDSB1952 V3 Layout: Maggie L.

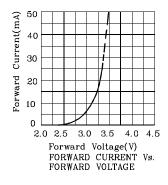


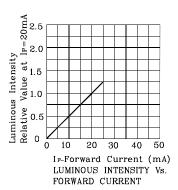


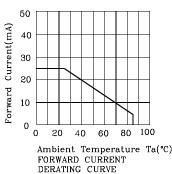


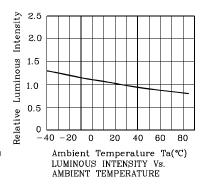


❖ DG



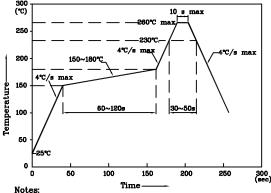






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

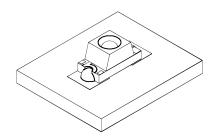


- notes:
 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

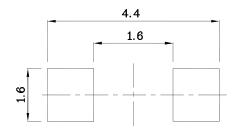




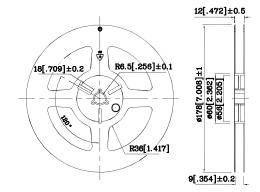
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



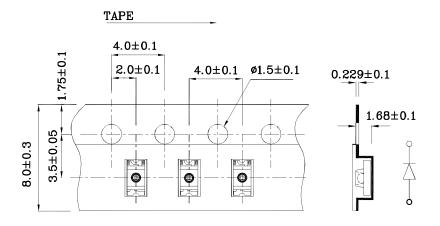
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Apr 23,2011 XDSB1952 V3 Layout: Maggie L.





PACKING & LABEL SPECIFICATIONS

